

Fig. 6 is a view for explaining a method of manufacturing a semiconductor device according to this invention.

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Fig. 7 is a view for explaining a method of manufacturing a semiconductor device according to this invention.

Fig. 8 is a view for explaining a method of manufacturing a semiconductor device according to this invention.

Fig. 9 is a view for explaining a method of manufacturing a semiconductor device according to this invention.

Fig. 10 is a view for explaining a conventional mounting structure for a circuit device. --

In the claims:

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Please cancel claim 4.

Please amend claims 1, 2, 5, 8, 11, 12, and 14 as follows:

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--1. (Amended) A semiconductor device comprising:

- a plurality of conductive paths electrically separated from one another by a trench;
- a first conductive path of said plurality of conductive paths, having a die pad shape;
- a semiconductor chip disposed on said first conductive path; said first conductive path coupled to said semiconductor chip through a thermally conductive material;
- a second conductive path disposed peripherally around said semiconductor chip, having a bonding pad shape;
- a third conductive path having a shape of an external connecting pad and coupled to said second conductive path, said third conductive path being disposed underneath said semiconductor chip and coupled to said semiconductor chip through an insulating material;
- connecting means for electrically connecting said semiconductor chip to said second conductive path;
- insulating resin covering said semiconductor chip, filling in the trench, and integrally supporting the semiconductor chip and the conductive paths with a bottom surface of the paths exposed.